

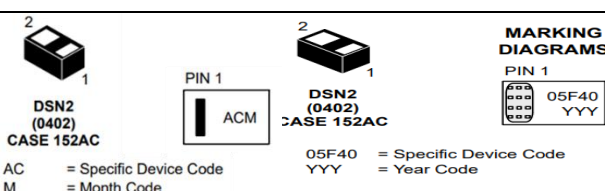
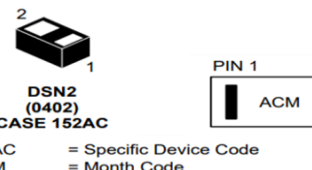
Title of Change:	Transfer of DSN2 Schottky plating site (from FCMS, China to HTKS, China) & Back End sites consolidation (from JCAP, ONSC, SBN to JCAP, ONSC)
Proposed First Ship date:	01 Jan 2024 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or NurulAliaFatin.Redzoan@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or NurulAkmar.MohdFauzi@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Affected products will be identified by date code
Change Category:	Assembly Change, Test Change
Change Sub-Category(s):	Manufacturing Site Transfer, Material Change

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Shenzhen, China	Huatian Technology, China
	JCAP, China

Description and Purpose:

Due to the acquisition of FCMS, China by HTKS, China FCMS will discontinue their support by Oct'2023. Therefore, **onsemi** is notifying its customers of its intent to transfer the plating site and consolidate the back-end sites of its DSN2 Schottky portfolio. The change will include the transfer of the plating site from external foundry facility, Flipchip Millenium (FCMS), China to external foundry facility, Huatian Technology (HTKS), China. Additionally, the back-end sites will be consolidated to onsemi Shenzhen, China and JCET Jiangyn (AVM) (JCAP), China. Other changes include a standardization of die top metal and standardization of product marking. Refer to the below table for details of changes by OPN:

	Before Change Description	After Change Description
Backgrind Site	onsemi ISMF, Malaysia	Huatian Technology, China
Front Metal	20kAlSiCu, 40kAlSi	20kAlSiCu
Marking Design	 DSN2 (0402) CASE 152AC ACM 05F40 YYY AC = Specific Device Code M = Month Code	 DSN2 (0402) CASE 152AC ACM AC = Specific Device Code M = Month Code
Plating Site	Flipchip Millenium (Shanghai)(FCMS), China JS Foundry, Japan	Huatian Technology, China



Final Product/Process Change Notification

Document #:FPCN25300X

Issue Date:31 Aug 2023

Probe, Tape & Reel Site	onsemi Seremban, Malaysia onsemi Shenzhen, China JCET Jiangyn BE(AVM)(JCAP), China	onsemi Shenzhen, China JCET Jiangyn BE(AVM)(JCAP), China
-------------------------	--	---

NOTE: Change table is attached.

To view attachments:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file/s

Reliability Data Summary:

QV DEVICE NAME: SNSR01F30NXT5G

RMS: S89606

PACKAGE: DSN2 (0201)

Test	Specification	Condition	Interval	Results
High Temperature Storage Life	JESD22-A103	Ta= 125°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/231
Temperature Cycling	JESD22-A104	Ta= -40°C to +125°C	850 cyc	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

QV DEVICE NAME: NSR20F40NXT5G

RMS: S89629

PACKAGE: DSN2 (0603)

Test	Specification	Condition	Interval	Results
High Temperature Storage Life	JESD22-A103	Ta= 125°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/231
Temperature Cycling	JESD22-A104	Ta= -40°C to +125°C	850 cyc	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NSR01F30NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR01L30NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR02F30NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G



Final Product/Process Change Notification

Document #:FPCN25300X

Issue Date:31 Aug 2023

NSR02L30NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
SNSR01F30NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR05F20NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR05F30NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR05F40NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
SNSR05F40NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR10F20NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR10F30NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR10F40NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR20F20NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
SNSR15304NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
SNSR20F30WCNXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
SNSR20F30WC1NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR20F40NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G
NSR20F30NXT5G	SNSR01F30NXT5G, NSR20F40NXT5G